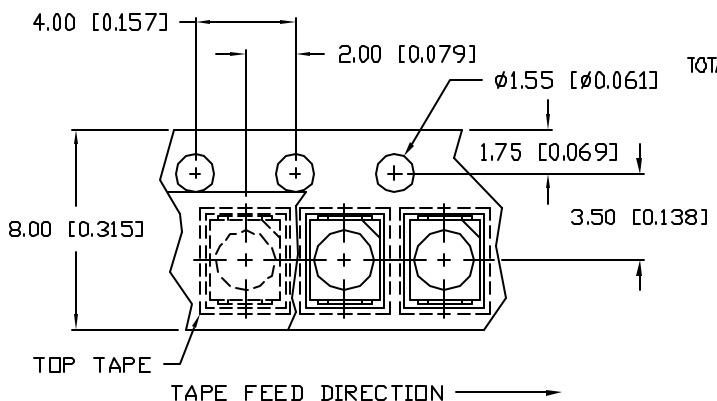
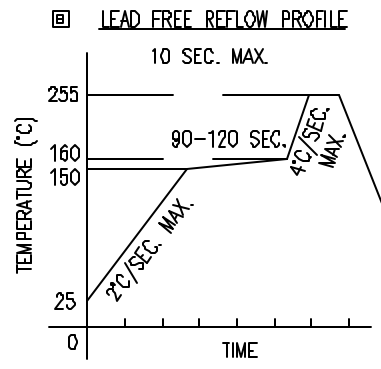
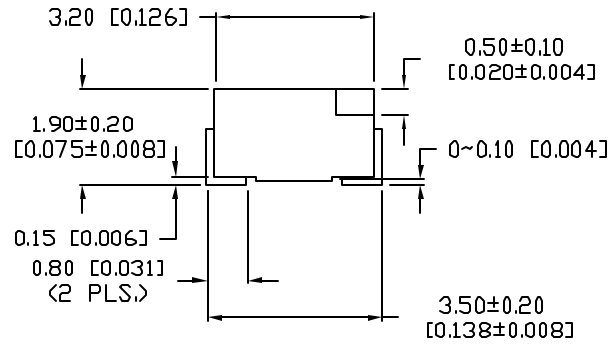
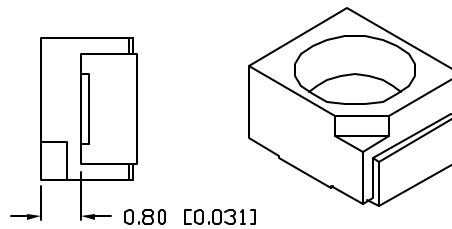
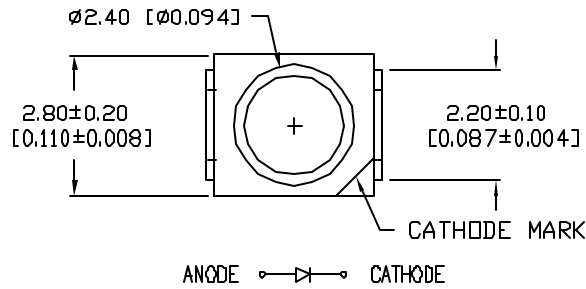
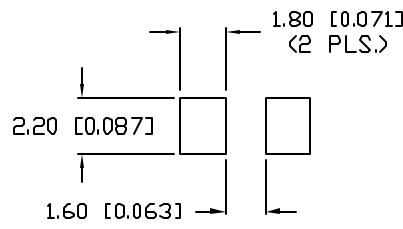


UNCONTROLLED DOCUMENT



RECOMMENDED SOLDER PAD LAYOUT



PART NUMBER		REV.
SML-LX2832IC-TR		C

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10801.	10.24.01
B	E.C.N. #10967.	3.14.03
C	E.C.N. #11148.	2.8.05

ELECTRO-OPTICAL CHARACTERISTICS  $T_A=25^\circ\text{C}$   $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		635		nm	
FORWARD VOLTAGE		2.0	2.5	$V_f$	
REVERSE VOLTAGE	5.0			$V_r$	$I_f=100\mu\text{A}$
AXIAL INTENSITY	10	25		mcd	$I_f=20\text{mA}$
VIEWING ANGLE		120		2x theta	
EMITTED COLOR:	RED				
EPOXY LENS FINISH:	WATER CLEAR				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	160	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	100	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING TEMP.	-40 TO +85	°C
STORAGE TEMP.	-40 TO +85	°C

\*  $t < 10\mu\text{s}$

NOTES:

- THE POLARITY MARK IS ORIENTED TOWARDS THE TAPE SPROCKET HOLE.

CAUTION: MOISTURE SENSITIVE DEVICE  
PER JEDEC LEVEL 4 STANDARDS



UNCONTROLLED DOCUMENT

\*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030), MIN= <sup>+DECIMAL PRECISION</sup> <sub>-0.00</sub> MAX= <sup>+0.00</sup> <sub>-DECIMAL PRECISION</sub>

REV.	PART NUMBER
C	SML-LX2832IC-TR

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2.8mm x 3.2mm SURFACE MOUNT LED WITH REFLECTOR,  
635nm RED LED, WATER CLEAR LENS,  
2,000 PIECES PER TAPE AND REEL.

RELIABILITY NOTE  
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY:	CHECKED BY:	APPROVED BY:	DATE:
JC			1.11.01
			PAGE: 1 OF 1
			SCALE: N/A